IN THE CLAIMS:

Cancel claim 2, and amend claims 1, 3-8 and 11-14 as shown on the following pages.

1. (Currently Amended) A system for maintaining an IC-module near a set-point temperature while electrical power dissipation is said IC-module is varied; said system being comprised of:

a container having an open end with a seal for pressing against said IC-module;

at least one nozzle, in said container; ~~, for spraying a liquid coolant on said IC-module when said seal is pressed against said IC-module; and,~~

at least one window, in said container; and, ~~, for passing electromagnetic radiation to said IC-module when said seal is pressed against said IC-module.~~

a closed-loop control means for - a) receiving a sensor signal representing a sensed temperature of said IC-module, b) cooling said IC-module, if said sensed temperature exceeds said set-point, by spraying a liquid coolant from said nozzle onto said IC-module, and c) heating said IC-module, if said set-point exceeds said sensed temperature, by sending electromagnetic radiation through said window onto said IC-module.

2. (Cancelled).

3. (Currently Amended) A system according to claim 1 [[2]] wherein said closed-loop control means sends said radiation through said window ~~generates said second control signal~~ with a ON-OFF ratio that increase as the difference between said set-point and said sensed temperature increases.

4. (Currently Amended) A system according to claim 1 [[2]] wherein said nozzle is replicated at spaced-apart locations in said container, and said window is replicated between said spaced-apart locations.

5. (Currently Amended) A system according to claim 1 [[2]] wherein said window is transparent to infrared radiation, but blocks said coolant in both a liquid state and a gas state.

6. (Currently Amended) A system according to claim 1 [[2]] wherein said nozzle is replicated at spaced-apart locations in said container, said closed-loop control means sends a control signal to each nozzle, and each nozzle ejects just a single droplet of said liquid coolant when it receives said ~~first~~ control signal.

7. (Currently Amended) A system according to claim 6 wherein said closed-loop control means sends said ~~first~~ control signal to all of said nozzles simultaneously with a frequency that increases as the difference between said sensed temperature and said set-point increases.

8. (Currently Amended) A system according to claim 6 wherein said closed-loop control means sends said ~~first~~ control signal to a subset of said nozzles simultaneously, and increase the number of nozzles in said subset as the difference between said sensed temperature and said set-point increases.

9. (Original) A system according to claim 6 wherein each nozzle ejects said droplet by squeezing said coolant with a piezoelectric device.

10. (Original) A system according to claim 6 wherein each nozzle ejects said droplet by heating said coolant with an electric heater.

11. (Currently Amended) A system according to claim 1 [[2]] wherein said closed-loop control means sends a control signal to each nozzle, and each nozzle sprays multiple droplets of said liquid coolant when it receives said ~~first~~ control signal.

12. (Currently Amended) A system according to claim 11 wherein said closed-loop control means generates said ~~first~~ control signal with an ON-OFF ratio that increases as the difference between said sensed temperature and said set-point increases.

13. (Currently Amended) A system according to claim 1 [[2]] wherein said seal is shaped to encircle a surface on said IC-module which enclosed an IC-chip.

14. (Currently Amended) A system according to claim 1 [[2]] wherein said seal is shaped to encircle an exposed surface on an IC-chip in said IC-module.